METHOD, APPARATUS AND COMPUTER PROGRAM PRODUCT FOR IMPLEMENTING ENHANCED HIGH FREQUENCY RETURN CURRENT PATHS UTILIZING DECOUPLING CAPACITORS IN A PACKAGE DESIGN

Abstract of the Disclosure

A method, apparatus and computer program product are provided for implementing high frequency return current paths utilizing decoupling capacitors within electronic packages. Electronic package physical design data are received for identifying a board layout. For each of a plurality of cells in a grid of a set cell size within the identified board layout, a respective number of signal vias are identified. A ratio of signal vias to return current paths is calculated for each of the plurality of cells. Each cell having a calculated ratio greater than a target ratio is identified. One or more decoupling capacitors are selectively added within each of the identified cells to provide high frequency return current paths.